

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (currently amended) A lead-free solder [comprising] consisting of 5 - 10 mass percent of Zn, a total of 0.005 - 1.0 mass percent of at least one substance selected from the group consisting of 0.005 - 0.1 mass percent of Au, 0.005 - 0.1 mass percent of Pt, 0.005 - 0.1 mass percent of Pd, 0.005 - 0.1 mass percent of Fe, and 0.005 - 1 mass percent of Sb, a total of 0 - 15 mass percent of at least one substance selected from Bi and In, and a remainder of Sn.

2. (original) A lead-free solder as claimed in claim 1 including a total of 0.01 - 0.7 mass percent of at least one substance selected from the group consisting of Au, Pt, Pd, Fe, and Sb.

3. (original) A lead-free solder as claimed in claim 1 including a total of 0.5 - 12 mass percent of at least one substance selected from the group consisting of Bi and In.

4. (previously presented) A solder paste formed by mixing a powder of a lead-free solder as claimed in claim 1 with a flux component.

5. (original) A solder paste as claimed in claim 4 wherein the flux component is a rosin flux.

6. (original) A solder paste as claimed in claim 5 wherein the rosin flux contains a halide.

7. (previously presented) A soldered article having a soldered portion which is soldered by a lead-free solder as claimed in claim 1.

8. (original) A soldered article as claimed in claim 7 wherein the soldered article is a printed circuit board having an electronic part mounted thereon by soldering.

9. (original) A soldered article as claimed in claim 8 wherein at least one of the electronic part and the printed circuit board has a soldered portion made of Cu.

10. (new) A lead-free solder as claimed in claim 1 including at least one of Pt, Pd, and Fe.

11. (new) A lead-free solder as claimed in claim 1 including Fe.

12. (new) A lead-free solder as claimed in claim 1 consisting of 5 - 10 mass percent of Zn, a total of 0.005 - 1.0 mass percent of at least one substance selected from the group

consisting of Au, Pt, Pd, Fe, and Sb, 0.5 - 12 mass percent of Bi, and a remainder of Sn.

13. (new) A lead-free solder as claimed in claim 12 including at least 2 mass percent of Bi.

14. (new) A lead-free solder as claimed in claim 13 including at most 10 mass percent of Bi.

15. (new) A lead-free solder as claimed in claim 1 consisting of 5 - 10 mass percent of Zn, 0.005 - 1.0 mass percent of Sb, a total of 0 - 15 mass percent of at least one of Bi and In, and a remainder of Sn.

16. (new) A lead-free solder as claimed in claim 1 consisting of 5 - 10 mass percent of Zn, at least one substance selected from the group consisting of 0.005 - 0.1 mass percent of Au, 0.005 - 0.1 mass percent of Pt, and 0.005 - 0.1 mass percent of Pd, a total of 0 - 15 mass percent of at least one substance selected from Bi and In, and a remainder of Sn.

17. (new) A lead-free solder as claimed in claim 1 including a total of 0.005 - 1.0 mass percent of at least one substance selected from the group consisting of 0.01 - 0.1 mass percent of Au, 0.005 - 0.1 mass percent of Pt, 0.005 - 0.1 mass percent of Pd, 0.01 - 0.1 mass percent of Fe, and 0.01 - 1 mass percent of Sb.